

ABSTRACT OF THE DISCLOSURE

A multilayered circuit board and a method of forming the multilayered circuit board are provided. In a first circuit forming process, a first circuit is formed on an insulating board with a conductor; in a circuit embedding process, the first circuit is embedded in the insulating board so as to have a predetermined surface flatness and a predetermined parallelism; in a masking process, a pilot hole for a via hole is masked at a part of a surface 5 of the circuit; in an insulating layer forming process P5p, an insulating material is applied as a layer to the surface except that portion thereof covered by the mask; in an insulating material layer flattening process, the surface of the insulating material layer is flattened so as to have the predetermined surface 10 flatness and the predetermined parallelism; and in a pilot hole forming process, the mask is removed. 15